



Applicant: Chen et al.
Application No.: 10/812,130

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Please amend the claims as follows.

Listing of Claims:

1. (Currently amended) A method for wiring connection, comprising steps of:

applying at least a barrel pin to a printed circuit board;
riveting one end of said barrel pin to said printed circuit board;
soldering said barrel pin on said printed circuit board;
inserting at least a wiring into said barrel pin having been soldered on said printed circuit board via the other end of said barrel pin; and
fixing said wiring inside said barrel pin by a taper recess formed on said barrel pin and above said printed circuit board.

2. (Original) The method according to claim 1, wherein said barrel pin and said printed circuit board are electrically soldered together through passing through an air reflow oven.

3. (Original) The method according to claim 1 further comprising a step of:

mounting at least an electronic element on said printed circuit board so as to be passed through an air reflow oven simultaneously with said printed circuit board and said barrel pin.

4. (Original) The method according to claim 1, wherein said wiring connection is a process for an electronic ballast.

5. (Previously Presented) The method according to claim 1, wherein said barrel pin is nickel-plated so that a wetting ability thereof becomes relatively worse.

6. (Original) The method according to claim 1, wherein said riveting step is performed by a first tool.

7. (Original) The method according to claim 1, wherein said fixing step is performed by a second tool.

8. (Previously Presented) The method according to claim 7, wherein said second tool is a taper tool for hitting said barrel pin to form said taper recess so as to fasten said wiring thereinside.

9. (Currently amended) A wiring connection device for a printed circuit board, comprising:

at least a barrel pin having one end directly riveted and soldered at said printed circuit board for an electrical connection between said printed circuit board and said barrel pin; and

at least a wiring fastened in said barrel pin by a taper recess formed on said barrel pin and above said printed circuit board for an electrical connection between said barrel pin and said wiring.

10. (Original) The device according to claim 9, wherein said barrel pin is riveted by a first tool.

11. (Original) The device according to claim 9, wherein said barrel pin is fitted by a second tool.

12. (Previously Presented) The device according to claim 11, wherein said second tool is a taper tool for fitting said barrel pin into said taper recess so as to fasten said wiring thereinside.

13. (Original) The device according to claim 9, wherein said barrel pin and said printed circuit board are electrically soldered together through passing through an air reflow oven.

14. (Original) The device according to claim 9, wherein said wiring connection device is used for an electronic ballast.

15. (Currently amended) A wiring connection device for a printed circuit board, comprising:

at least two barrel pins mounted at a side of said printed circuit board, and being directly riveted and soldered thereon for an electrical connection between said barrel pins and said printed circuit board; and

at least a wiring fastened in said barrel pins by a taper recess formed on said barrel pin and above said printed circuit board for an electrical connection between said barrel pins and said wiring.

Applicant: Chen et al.
Application No.: 10/812,130

16. (Previously Presented) The method according to claim 1 wherein the applying the barrel pin to the printed circuit board, the riveting the barrel pin to the printed circuit board, and the soldering the barrel pin into the printed circuit board are performed before the inserting the wiring into the barrel pin and fixing the wiring inside the barrel pin by the taper recess.